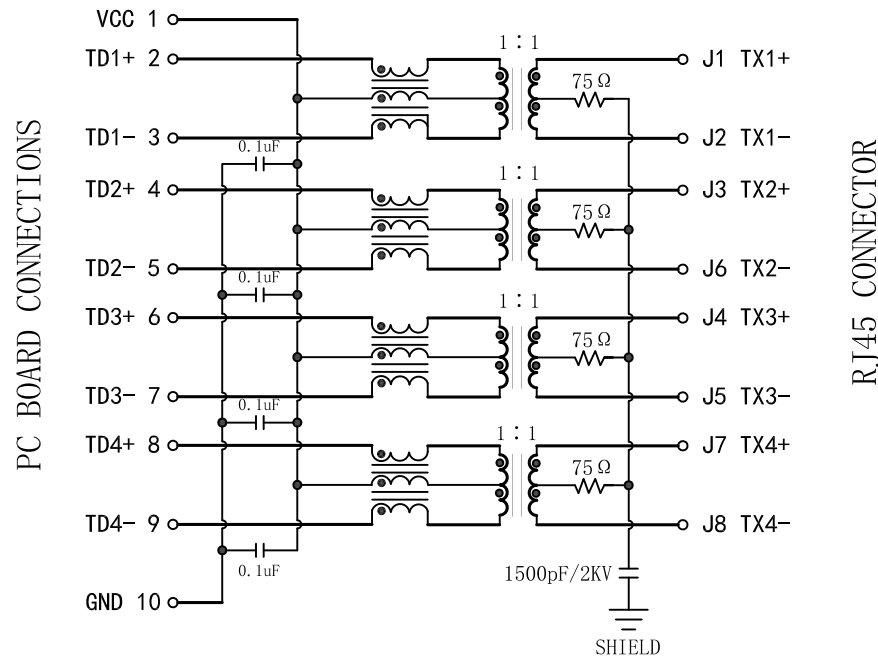


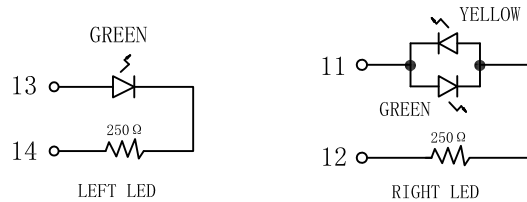
Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2015-05-19	



ELECTRICAL SPECIFICATIONS @25°C

- Turn Ratio($\pm 3\%$):
Pri:Sec = 1CT:1CT
- Inductance OCL:
350uH MIN @ 100KHz 0.1V 8mA DC Bias
- DCR: 1.2 Ω MAX
- Insertion Loss:
-1.0dB MAX @ 1-100MHz
- Return Loss:
-18dB MIN @ 1-30MHz
-15dB MIN @ 30-60MHz
-12dB MIN @ 60-100MHz
- Cross talk:
-40dB MIN @ 30MHz
-35dB MIN @ 60MHz
-30dB MIN @ 100MHz
- Common Mode Rejection:
-30dB MIN @ 1-100MHz
- Hipot Test: 1500Vrms
- Operating Temperature Range: 0°C TO 70°C

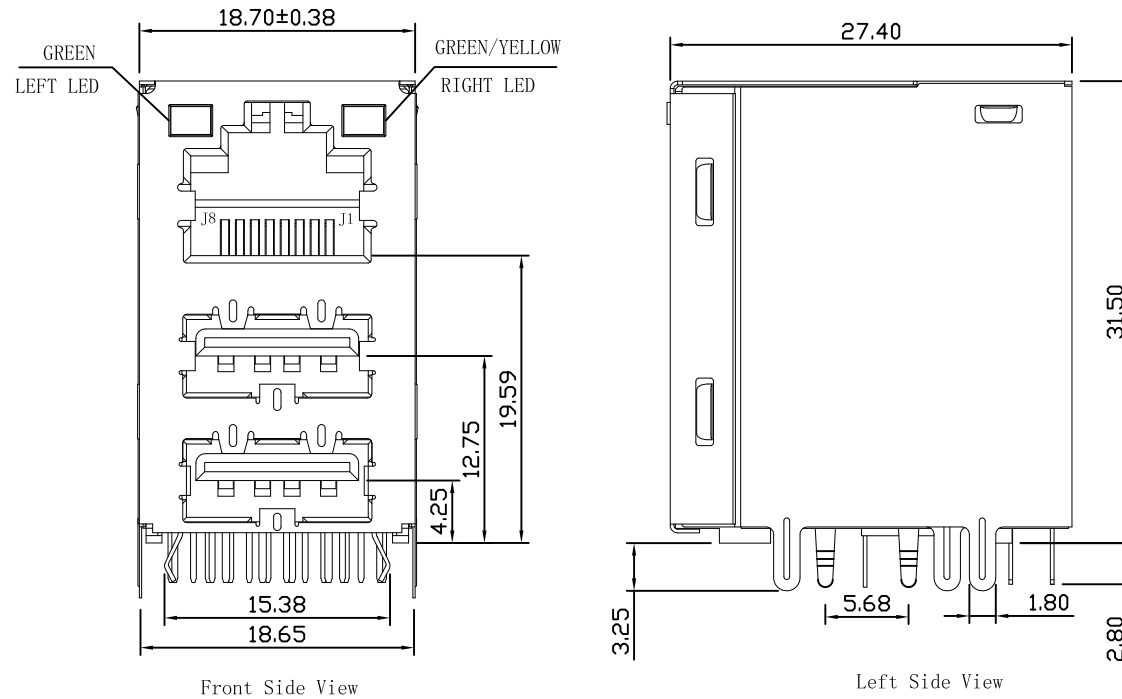


Emitting Color	λ p(nm)	VF@IF=20mA	IR @VR=5V
GREEN	565	1.8~2.4V	10 μ A max
YELLOW	585	1.8~2.4V	10 μ A max



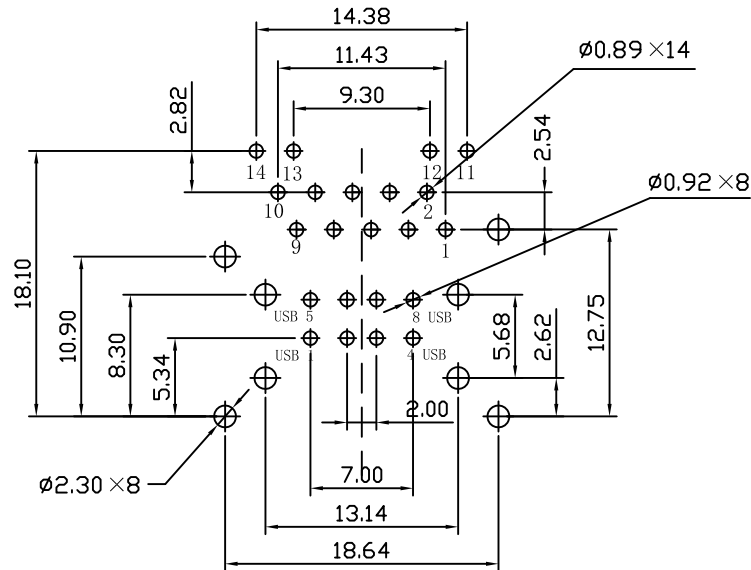
X:X	± 0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	± 0.25	CHKD:	TITLE: RJ45 Connector with 1000 Base-TX Jack/Dual USB Combo	
X:XXX	± 0.05	DR: TOM	PART NO. : LPJU5303B50NL	
ANGLES	$\pm 1^\circ$	UNIT: mm		
	SCALE: 2/1	SHEET: 1/2	REV: A	DWG NO. : LP15051936

Mechanical:



Front Side View

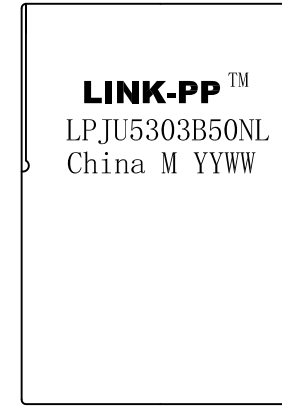
Left Side View



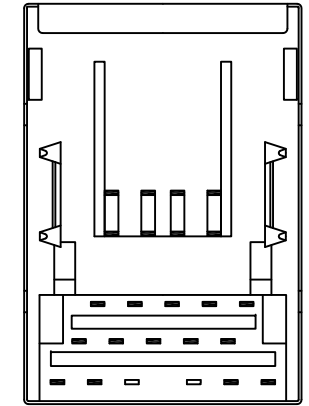
Suggested PCB Layout (Top View)



REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2015-05-19	



Top Side View



Bottom Side View

NOTES:

1. Designed to support application, such as SOHO (ADSL modems), LAN-on-Motherboard (LOM), hub and Switches.
2. Meets IEEE 802.3 specification
3. Connector Materials:
 Housing Material: Thermoplastic PBT+30%G.F UL94V-0
 Contact Material: Phosphor Bronze C5210R-EH Thickness=0.35mm
 Pins: Brass C2680R-H Thickness=0.35mm
 Shield: SUS 201-1/2H Thickness=0.35mm
 Contact plating: Gold 6 micro-inches min. In contact area.
 USB Contact plating: Gold Flash.
4. Wave solder tip temperature: 265°C Max, 5 Sec.
5. UL Certification: File Number E484635.

X:X	±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	±0.25	CHKD:	TITLE: RJ45 Connector with 1000 Base-TX Jack/Dual USB Combo	
X:XXX	±0.05	DR: TOM	PART NO.: LPJU5303B50NL	
ANGLES	±1°	UNIT: mm	DWG NO.: LP15051936	
	SCALE: 2/1	SHEET: 2/2	REV: A	